

**LTM9002 108LD 15.00mm X 11.25mm X 2.32mm (TABLE OF MATERIAL DECLARATION)**

*The LTM9002 is RoHS compliant per EU RoHS Directive 2003/95/EC.*

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1748	Barium Compounds	7727-43-7	0.00262	1.50000
				Filler Substances (Silica Crystalline)	-	0.06976	39.91457
				Copper Metal	7440-50-8	0.09788	56.00000
				Copper Compounds	1328-53-6	0.00003	0.01800
				Ecotoxic substances	7439-92-1	0.00000	0.00043
				Gold metal or alloy	7440-57-5	0.00080	0.46000
				Nickel	7440-02-0	0.00367	2.10000
				Zinc	7440-66-6	0.00001	0.00700
2	Solder Paste	Alloy	0.0148	Sn	7440-31-5	0.01408	95.00000
				Sb	7440-36-0	0.00074	5.00000
3	Die attach adhesive	Epoxy Resin	0.0053	epoxy	—	0.00530	100.00000
4	Passive/Active Components		0.0623	Capacitor	-	0.05564	89.30188
				Resistor	-	0.00667	10.70294
				Inductor	-	0.00000	0.00000
				Diode	-	0.00000	0.00000
5	Active Ics	Silicon	0.0062	Silicon	7440-21-3	0.00624	100.00000
6	Wire	Gold	0.0020	Au	7440-57-5	0.00204	99.99000
7	LTC6400IUD-8	see LTC web site for	0.0409	see LTC website	—	0.04090	
6	Encapsulation	Epoxy Resin	0.6247	Fused Silica	60676-86-0	0.48227	77.20000
				Epoxy Resin	-	0.05560	8.90000
				Phenol Resin	-	0.05560	8.90000
				Crytalline Silica	14808-60-7	0.01874	3.00000
				Carbon Black	1333-86-4	0.00312	0.50000
				Metal Hydroxide	-	0.00937	1.50000
Total Package Weight			0.9311				

Note: Composition derived from MSDS and material C of C from Vendors  
 Component Weight based on assembly of generic parts